



TEAM PACIFIC CORPORATION

SEMICONDUCTOR
ASSEMBLY AND TEST

BREAKTHROUGH
POWER PACKAGING
SOLUTIONS

SYSTEM REPORT

DATE : 16 - November - 2023
TO : Patrocinio G. Olarte / Andrew D. Lumitan / Anthony N. Teng
CC : Emmanuel G. Natividad
NOTED BY : Guillermo Y. Teodoro
REVIEWED BY : Gianni Paula V. Rejano
FROM : Carol A. Guanzon
SUBJECT : **Billing Request System (Request for Development)**



Application

:



Complete Process



Partial / Turn-over



Report

I. Project Objectives

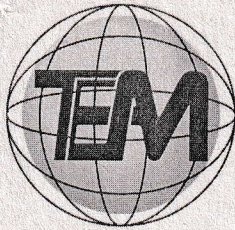
- To automate the generation of billing request.
- To monitor add on billings from the request up to the payment.

II. Background

- There are different types of billing requests, and it comes from different sources with different procedures and documentation.
- A manual monitoring was implemented Q2 this year and some of the projects requested to our group are all about automation of billing report. This resulted in starting the development of billing request and monitoring system.

III. Project Details

- The process mapping for the billing request system started 1st week of September. This involves the Finance and all source department of the billing requests.
- See below attachments for the baseline and design requirements:



TEAM PACIFIC CORPORATION

SEMICONDUCTOR
ASSEMBLY AND TEST

BREAKTHROUGH
POWER PACKAGING
SOLUTIONS

Attachments A - Billing Request Non-Trade Flowchart (Actual Process)

Attachments B - Billing Request Trade Flowchart (Actual Process)

Attachments C - Billing Request ERD (Actual Process)

Attachments D - Billing Request System Wireframe

Attachments E - Billing Request ERD of System (Design)

Attachments F - Billing Request System Flowchart (Design)

IV. Project Recommendation

- Presentation and approval of the design (ECD: W2-W3 of November 2023).
- Approved design to be provided to MIS for developments

V. Project Timeline

- The development started on November 15, 2023 and the estimated completion date is February 1, 2024.